

MPS-U55 (SILICON) MPS-U56

PNP SILICON ANNULAR AMPLIFIER TRANSISTORS

... designed for general-purpose, high-voltage amplifier and driver applications.

- High Collector-Emitter Breakdown Voltage –
 $V_{CE0} = 60 \text{ Vdc (Min) @ } I_C = 1.0 \text{ mAdc} - \text{MPS-U55}$
 $80 \text{ Vdc (Min) @ } I_C = 1.0 \text{ mAdc} - \text{MPS-U56}$
- High Power Dissipation – $P_D = 10 \text{ W @ } T_C = 25^\circ\text{C}$
- Complements to NPN MPS-U05 and MPS-U06

PNP SILICON AMPLIFIER TRANSISTORS

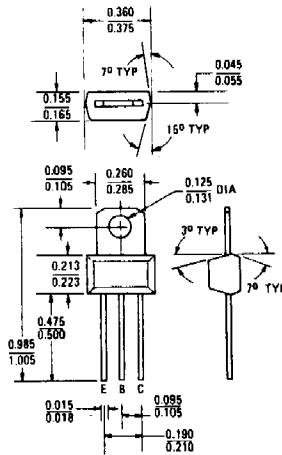


MAXIMUM RATINGS

Rating	Symbol	MPS-U55	MPS-U56	Unit
Collector-Emitter Voltage	V_{CE0}	60	80	Vdc
Collector-Base Voltage	V_{CB}	60	80	Vdc
Emitter-Base Voltage	V_{EB}	4.0		Vdc
Collector Current – Continuous	I_C	2.0		Adc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	1.0	8.0	Watt mW/ $^\circ\text{C}$
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	10	80	Watts mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +150		$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	θ_{JC}	12.5	$^\circ\text{C/W}$
Thermal Resistance, Junction to Ambient	θ_{JA}	125	$^\circ\text{C/W}$

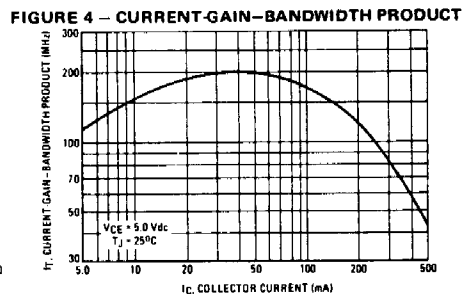
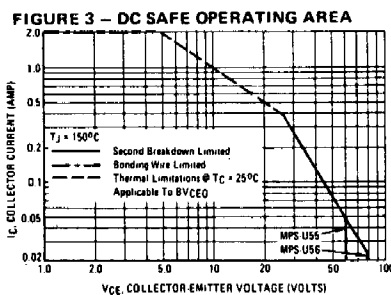
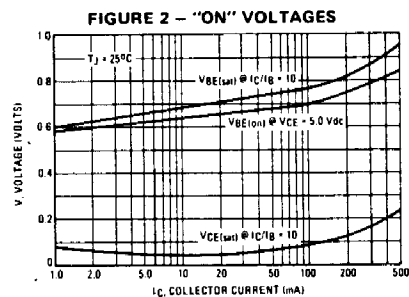
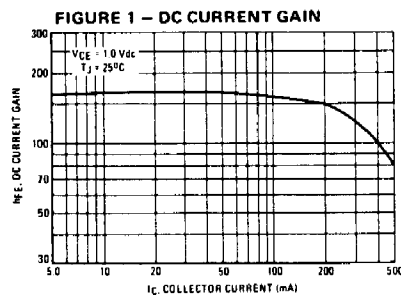


MPS-U55, MPS-U56 (continued)

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage ($I_C = 1.0 \text{ mAdc}, I_B = 0$)	BV_{CEO}	60 80	— —	— —	Vdc
Emitter-Base Breakdown Voltage ($I_E = 100 \mu\text{Adc}, I_C = 0$)	BV_{EBO}	4.0	—	—	Vdc
Collector Cutoff Current ($V_{CB} = 40 \text{ Vdc}, I_E = 0$) ($V_{CB} = 60 \text{ Vdc}, I_E = 0$)	I_{CBO}	— —	— —	100 100	nAdc
ON CHARACTERISTICS					
DC Current Gain (1) ($I_C = 50 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}$) ($I_C = 250 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}$) ($I_C = 500 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}$)	h_{FE}	80 50 —	160 130 80	— — —	—
Collector-Emitter Saturation Voltage(1) ($I_C = 250 \text{ mAdc}, I_B = 10 \text{ mAdc}$) ($I_C = 250 \text{ mAdc}, I_B = 25 \text{ mAdc}$)	$V_{CE(sat)}$	— —	0.22 0.15	0.5 —	Vdc
Base-Emitter On Voltage (1) ($I_C = 250 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}$)	$V_{BE(on)}$	—	0.78	1.2	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain-Bandwidth Product ($I_C = 200 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}, f = 100 \text{ MHz}$)	f_T	50	100	—	MHz
Output Capacitance ($V_{CB} = 10 \text{ Vdc}, I_E = 0, f = 100 \text{ kHz}$)	C_{ob}	—	10	15	pF

(1) Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.



There are two limitations on the power handling ability of a transistor: junction temperature and secondary breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 3 is based on $T_{J(pk)} = 150^\circ\text{C}$; T_C is variable depending on conditions. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by secondary breakdown.

